

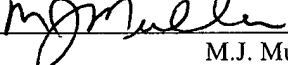
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s)	Wang	Examiner:	Warren, Matthew E.
Serial No.:	10/736,486	Group Art Unit:	2815
Confirmation No.:	1290	Docket:	669-77 CON/CIP
Filed:	December 15, 2003	Dated:	March 23, 2005
For:	HIGH DENSITY INTEGRATED CIRCUITS AND THE METHOD OF PACKAGING THE SAME		

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

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On: March 23, 2005*

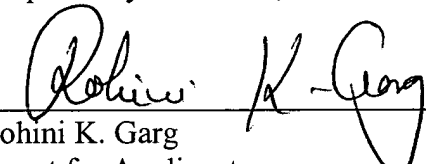
By: 
M.J. Mullin

TRANSMITTAL OF FORMAL DRAWINGS

Sir:

Attached please find five (5) sheets of formal drawings for the above-referenced application.

Respectfully submitted,


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